

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10719218			
<b>Filing Date:</b>	20-Nov-2003			
<b>Title of Invention:</b>	STRUCTURE, MATERIAL, AND DESIGN FOR ASSEMBLING A LOW-K SI DIE TO ACHIEVE AN INDUSTRIAL GRADE RELIABILITY WIRE BONDING PACKAGE			
<b>First Named Inventor/Applicant Name:</b>	Wen-Chou Vincent Wang			
<b>Filer:</b>	CINDY H. SHU/Valerie Olsen			
<b>Attorney Docket Number:</b>	ALTRP100/A1198			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appt Issue fee	1501	1	1440	1440
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Printed copy of patent - no color	8001	2	3	6
<b>Total in USD (\$)</b>				<b>1446</b>